


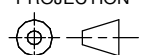
SCALE 25:1

Notes: (Unless Otherwise Specified).

- 1) DIE MATERIAL IS SILICON.
- 2) DIE THICKNESS IS 250 μm (10 MIL).
- 3) METALLIZATION 1.0 μm ALUMINUM (Al) OVER 0.75 μm SiO_2 .
- 4) DIE IS WITHOUT PASSIVATION.
- 5) WIRE BONDABLE WITH GOLD (Au) OR ALUMINUM (Al) WIRE.
- 6) DAISY CHAIN PAIRS (8 PLACES).
- 7) TOLERANCE = $\pm 1 \mu\text{m}$.

DIMENSIONS IN MICRONS
1000 μm = 1.0mm

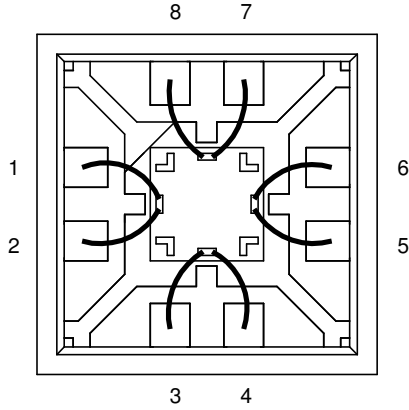
PART NUMBER SYSTEM						
TD	-	8	-	1.0	-	DC
SILICON TEST DIE	BOND PADS	DIE SIZE (mm)	DAISY CHAIN			

TOLERANCE UNLESS NOTED		APPROVALS	DATE				
X.XX	+/- 0.01	DRAWN J. HINES	2/26/2011				
X.XXX	+/- 0.005						
X.XXXX	+/- 0.0005			ENG		SCALE	SIZE
ALL DIMENSIONS IN		MFG		100:1	A	151008	A
<input checked="" type="checkbox"/> INCHES <input type="checkbox"/> MILLIMETERS		QA		DO NOT SCALE DRAWING SHEET 1 OF 2			
THIRD ANGLE PROJECTION		CUST					
		REVISED					

DAISY CHAIN WIRE BOND PATTERNS QFN PACKAGE

NET LIST
DCW10081

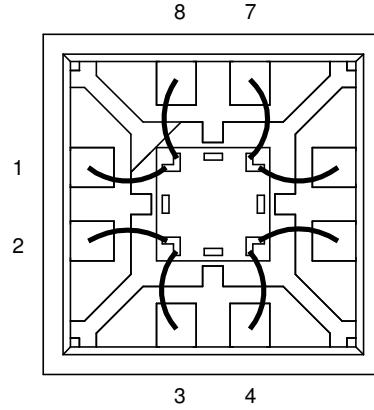
- 1-2
- 3-4
- 5-6
- 7-8



QFN8W.65-DCW10081
8L - 3X3mm

NET LIST
DCW10082

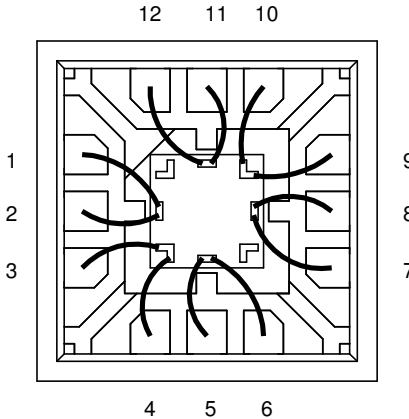
- 2-3
- 4-5
- 6-7
- 8-1



QFN8W.65-DCW10082
8L - 3X3mm

NET LIST
DCW10121

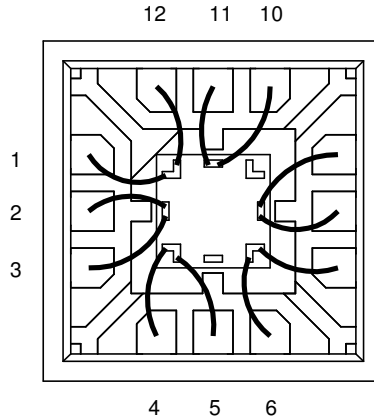
- 1-2
- 3-4
- 5-6
- 7-8
- 9-10
- 11-12



QFN12W.5-DCW10121
12L - 3X3mm

NET LIST
DCW10122

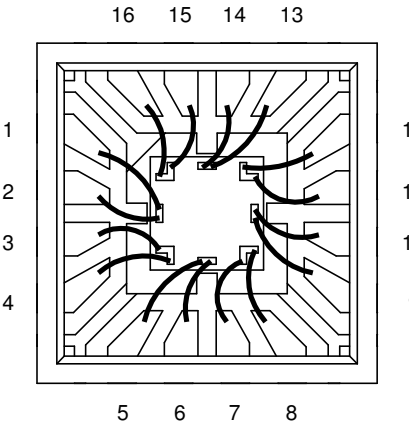
- 2-3
- 4-5
- 6-7
- 8-9
- 10-11
- 12-1



QFN12W.5-DCW10122
12L - 3X3mm

NET LIST
DCW10161

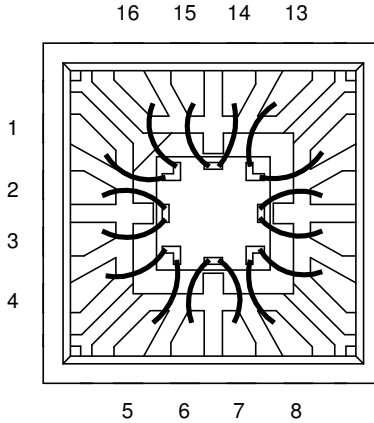
- 1-2
- 3-4
- 5-6
- 7-8
- 9-10
- 11-12
- 13-14
- 15-16



QFN16W.5-DCW10161
16L - 3X3mm

NET LIST
DCW10162

- 2-3
- 4-5
- 6-7
- 8-9
- 10-11
- 12-13
- 14-15
- 16-1



QFN16W.5-DCW10162
16L - 3X3mm

DIMENSIONS IN MICRONS
1000 μm = 1.0mm

TEST DIE			
TD	8	1.0	DC
SILICON TEST DIE	BOND PADS	DIE SIZE (mm)	DAISY CHAIN

TopLine[®]

TITLE				SI TEST DIE TD SERIES			
SCALE	15:1	SIZE	A	DRAWING NO.	151008	REV	A
DO NOT SCALE DRAWING						SHEET 2 OF 2	